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September 2015

FDS89161

Dual N-Channel Shielded Gate PowerTrench® MOSFET 100 V, 2.7 A, 105 m Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)}$ = 105 m Ω at V_{GS} = 10 V, I_D = 2.7 A
- Max $r_{DS(on)}$ = 171 m Ω at V_{GS} = 6 V, I_D = 2.1 A
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- 100% UIL Tested
- RoHS Compliant

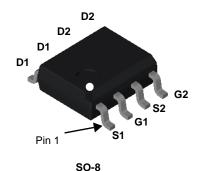


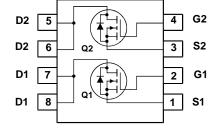
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for r_{DS(on)}, switching performance and ruggedness.

Applications

- Synchronous Rectifier
- Primary Switch For Bridge Topology





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Paramete	er		Ratings	Units
V _{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
1	Drain Current -Continuous			2.7	^
ID	-Pulsed			15	Α
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	13	mJ
D	Power Dissipation	T _C = 25 °C		31	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note1a)	1.6	VV
T _J , T _{STG}	Operating and Storage Junction Temperature	re Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS89161	FDS89161	SO-8	13 "	12 mm	2500 units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV_DSS	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		67		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	3	4	V
$\Delta V_{GS(th)}$ ΔT_J	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-9		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 2.7 \text{ A}$		86	105	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 2.1 \text{ A}$		120	171	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 2.7 \text{ A}, T_J = 125 ^{\circ}\text{C}$		144	176	
9 _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 2.7 \text{ A}$		5		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 50 V V 0 V	158	210	pF
C _{oss}	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{MHz}$	43	58	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112	3	5	pF
R_a	Gate Resistance		1		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time				4.2	10	ns
t _r	Rise Time		V_{DD} = 50 V, I_{D} = 2.7 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		1.3	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN} :			7.3	15	ns
t _f	Fall Time				1.9	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V			3	4.1	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 V to 5 V$	$V_{DD} = 50 \text{ V},$		1.7	2.4	
Q _{gs}	Gate to Source Charge		$I_D = 2.7 \text{ A}$		0.8		nC
Q_{gd}	Gate to Drain "Miller" Charge				0.8		nC

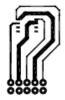
Drain-Source Diode Characteristics

V _{SD}	1Source to Drain Dioge Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.7 \text{ A}$	(Note 2)	0.85	1.3	\/
		$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$	(Note 2)	0.82	1.2	V
t _{rr}	Reverse Recovery Time	-I _F = 2.7 A, di/dt = 100 A/μs		34	54	ns
Q _{rr}	Reverse Recovery Charge			21	34	nC

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a) 78°C/W when mounted on a 1 in² pad of 2 oz copper



b) 135°C/W when mounted on a minimun pad

^{1.} R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{θCA} is determined by the user's board design.

^{2.} Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%. 3. Starting T $_J=25^{\circ}C,\;L=3$ mH, I $_{AS}=3$ A, V $_{DD}=\;100$ V, V $_{GS}=10$ V.

Typical Characteristics (N-Channel) T_J = 25°C unless otherwise noted

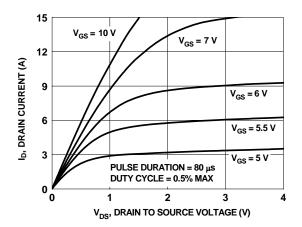


Figure 1. On-Region Characteristics

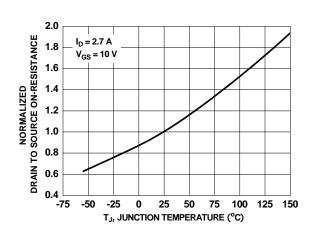


Figure 3. Normalized On-Resistance vs Junction Temperature

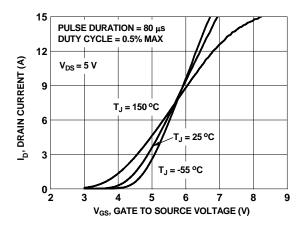


Figure 5. Transfer Characteristics

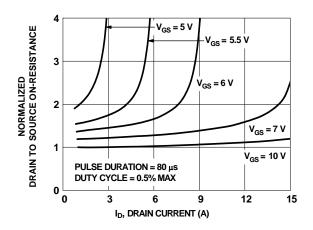


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

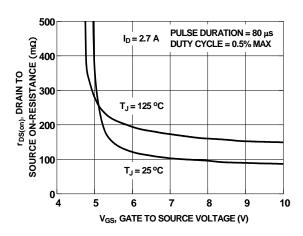


Figure 4. On-Resistance vs Gate to Source Voltage

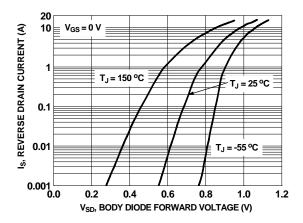


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

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Typical Characteristics (N-Channel) T_J = 25°C unless otherwise noted

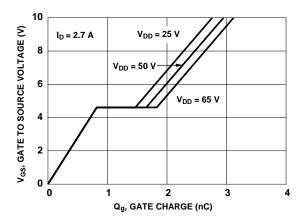


Figure 7. Gate Charge Characteristics

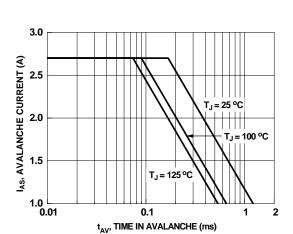


Figure 9. Unclamped Inductive Switching Capability

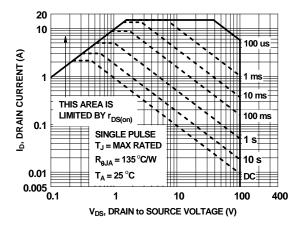


Figure 11. Forward Bias Safe Operating Area

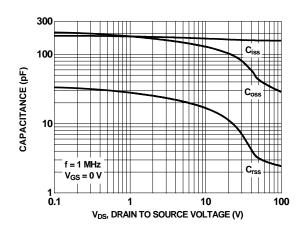


Figure 8. Capacitance vs Drain to Source Voltage

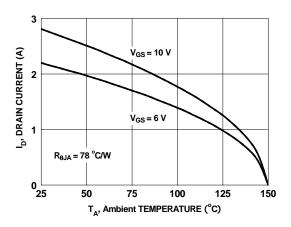


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

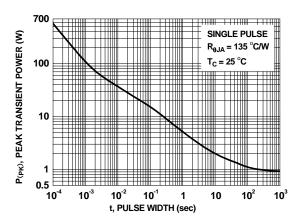


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics (N-Channel) $T_J = 25$ °C unless otherwise noted

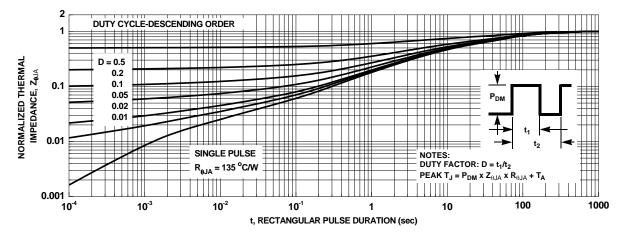
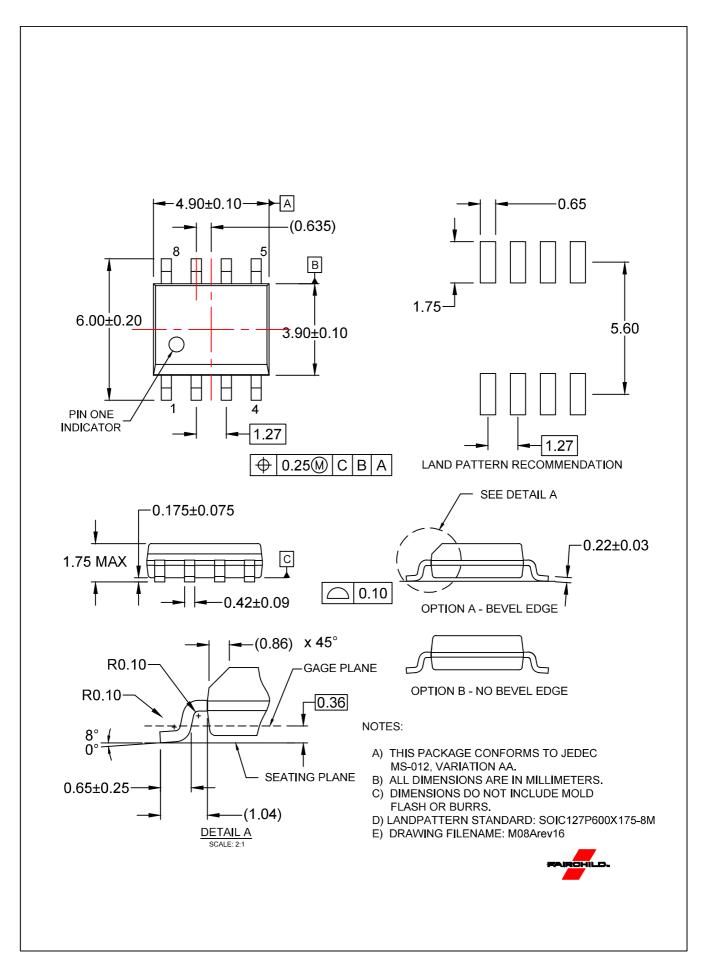


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

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